

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

What is claimed is:

1. (canceled)
2. (currently amended) A method according to claim 1, wherein for creating [[the]] a raised SMD pad comprises the steps of:
providing a pad face disposed above a surface of a laminate electronic circuit board
forming a base bump on the laminated electronic circuit board;
covering the base bump with a conductive bump layer, wherein the conductive bump layer covers the base bump and forms an extended edge around a perimeter of the base bump; and
layering a surrounding material over the extended edge of the conductive bump layer.
3. (original) A method according to claim 2, wherein forming the base bump further comprises creating an area of a conductive metal.
4. (original) A method according to claim 2, wherein forming the base bump further comprises exposing an area of an organic material.
5. (original) A method according to claim 4, wherein exposing the area of the organic material further comprises exposing an area of a material selected from a group comprising a solder mask material or a built-up dielectric material.

6. (original) A method according to claim 4, wherein exposing the area of the organic material comprises:

dispensing the organic material over an insulating layer on the surface of the substrate; and
removing a portion of the organic material.

7. (original) A method according to claim 2, wherein covering the base bump with a conductive bump layer further comprises covering the base bump with a material selected from a group consisting of copper, aluminum, gold, silver and nickel.

8. (original) A method according to claim 2, wherein layering the surrounding material over the extended edge of the conductive bump layer further comprises the steps of:

applying the surrounding material over the conductive bump layer; and
removing a portion of the surrounding material to expose the pad face and
at least a portion of the sides of the conductive bump layer.

9. (original) A method according to claim 8, wherein applying the surrounding material over the conductive bump layer further comprises applying a solder mask material over the conductive bump layer.

10. (original) A method according to claim 8, wherein removing a portion of the surrounding material further comprises subjecting the surrounding material to a photolithography process.

11. (original) A method according to claim 8, wherein removing a portion of the surrounding material comprises subjecting the surrounding material to a laser-drill process.

12-25. (canceled)